

**Final Program**

**Future Directions in IC and Package Design Workshop (FDIP)**

**October 28, 2007, Atlanta, GA**

sponsored by:



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AND MANUFACTURING  
TECHNOLOGY SOCIETY**

**IEEE**



organized by:

**CPMT Technical Committee on Electrical Design, Modeling, and Simulation (TC-EDMS)**

1:15pm - 1:30 pm **Welcome Remarks, Alina Deutsch, IBM, Madhavan Swaminathan, GIT**

**SESSION I: SYSTEM DESIGN**

**1:30pm – 4:00 pm**

Session Chair: George Katopis – IBM Corporation

1:30pm – 2:05pm “Signal Bandwidth for High Performance Computing” – Dale Becker, IBM Corp.

2:05pm – 2:40pm “Wireless Proximity Communications for 3D System Integration” –

Tadahiro Kuroda, Keio University

2:40pm – 3:15pm “A Critical Assessment of the State of the Art in Multiscale Multiphysics Modeling of Microelectronics - Jayathi Murthy, Purdue University

**3:15 – 4:00 pm - Refreshment Break**

**SESSION II: POWER DISTRIBUTION**

**4:00pm – 5:55 pm**

Session Chair: Gregory Taylor, Intel Corporation

4:00pm – 4:35pm “Power Delivery Challenges for Mobile Platforms” – Tawfik Arabi, Intel Corp.

4:35pm – 5:10pm “Modeling Challenges for Power Distribution Analysis” – Madhavan Swaminathan, Georgia Institute of Technology

5:10pm – 5:45pm “Power Delivery System Design Challenges and Explorations on How to Overcome Them” - Jiayuan Fang, Sigrity, Inc.

**5:45pm – 5:55 pm Closing Remarks, Madhavan Swaminathan, GIT, Alina Deutsch, IBM**

*Held just prior to the* **Electrical Performance of Electronic Packaging Conference**  
**October 29-31, 2007**

Visit [www.epep.org](http://www.epep.org) for full information and to register.